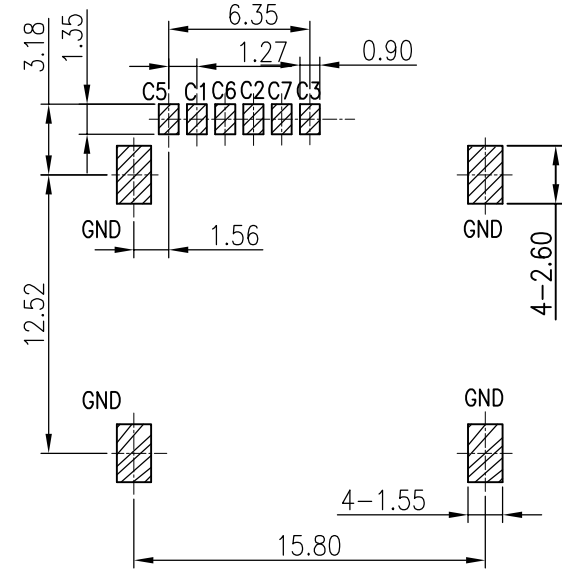
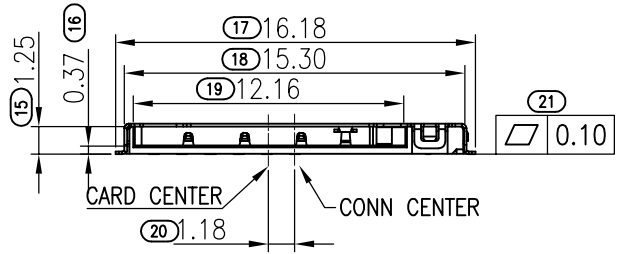
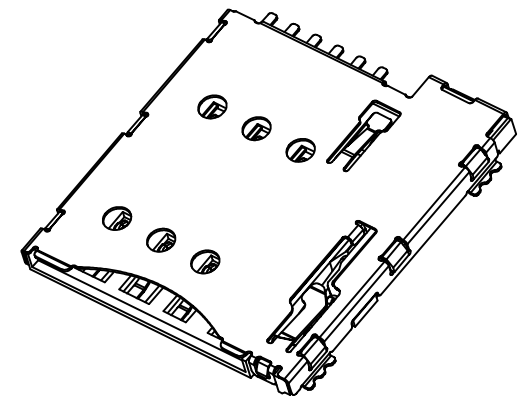
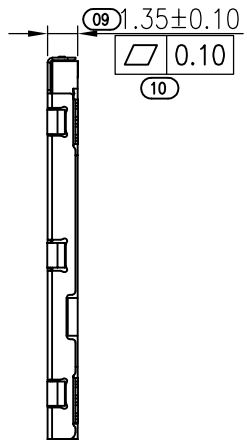
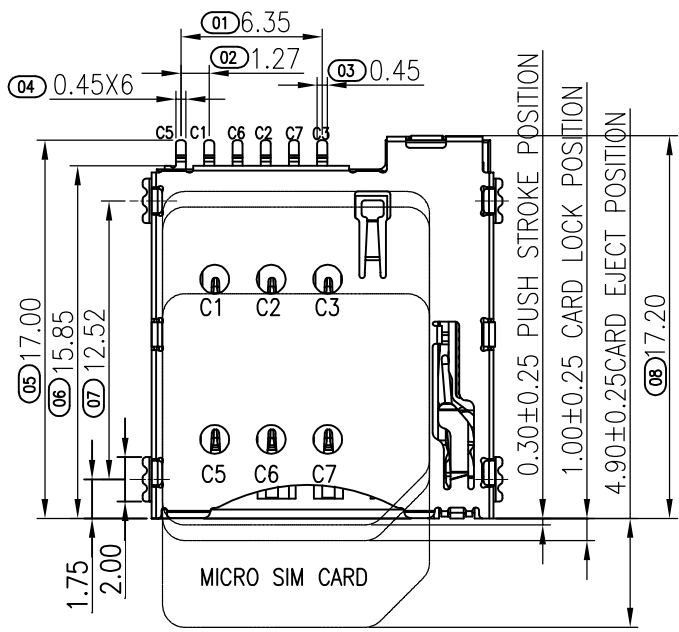


REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A0			RELEASE TO CUSTOMER	080505	HANG
A2					HANG



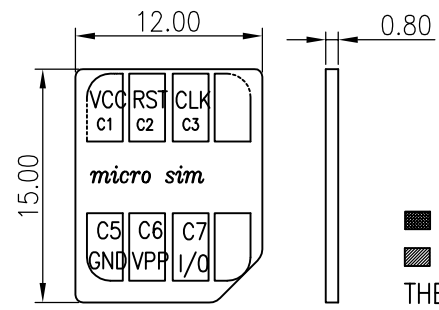
NOTES:

MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:
 Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area

Electrical:
 Current Rating :0.5A AC/DC max.
 Voltage Rating :50V AC/DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5'

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

MICRO SIM CARD

DIM	TOL	DIM	TOL
X.	±0.30	X".	±4.0"
X.X	±0.25	X.X"	±3.0"
X.XX	±0.20	X.XX"	±2.0"
X.XXX	±0.10	X.XXX"	±1.0"

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LASTAR

Lastar Technology CO., LTD

FILE NO		DATE	PRODUCT NAME: MICRO-SIM PUSH/PUSH 6PIN 1.35无柱、无候测(卡扣、有弹片、避位)		
DESIGN	HANG	080505	PART NUMBER SIM-080-1317-06Z9		SHORT CODE : 10300020
CHECK	WANGCM	080506	UNIT: mm	SHEET: N/A	MODEL:
APPROVED	HUYX	080506			REV. A2 SCALE N/A